Unit: mm

TOSHIBA Power MOS FET Module Silicon N Channel MOS Type (Four L<sup>2</sup>-π-MOSV inOne)

# **MP4210**

High Power, High Speed Switching Applications
For Printer Head Pin Driver and Pulse Motor Driver
For Solenoid Driver

- 4-V gate drivability
- Small package by full molding (SIP 10 pins)
- High drain power dissipation (4-device operation)  $: P_T = 4 \ W \ (Ta = 25^{\circ}C)$
- Low drain-source ON resistance: RDS (ON) =  $0.12 \Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 5.0 \text{ S (typ.)}$
- Low leakage current: IGSS =  $\pm 10~\mu A~(max)~(VGS = \pm 16~V)$  IDSS =  $100~\mu A~(max)~(VDS = 60~V)$
- Enhancement-mode:  $V_{th} = 0.8 \text{ to } 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

### **Maximum Ratings (Ta = 25°C)**

Characteristics		Symbol	Rating	Unit
Drain-source voltage		$V_{DSS}$	60	V
Drain-gate voltage ( $R_{GS}$ = 20 kΩ)		$V_{DGR}$	60	V
Gate-source voltage	Gate-source voltage		±20	V
	DC	I <sub>D</sub>	5	
	Pulse	$I_{DP}$	20	
Drain power dissipation (1-device operation, Ta = 25°C)		P <sub>D</sub>	2.0	W
Drain power dissipation (4-device operation, Ta = 25°C)		P <sub>DT</sub>	4.0	W
Single pulse avalanche energy (Note 1)		E <sub>AS</sub>	129	mJ
Avalanche current		I <sub>AR</sub>	5	Α
	1-device operation	E <sub>AR</sub>	0.2	
	4-device operation	E <sub>ART</sub>	0.4	
Channel temperature		T <sub>ch</sub>	150	°C
Storage temperature range		T <sub>stg</sub>	−55 to 150	°C

Note 1: Condition for avalanche energy (single pulse) measurement  $V_{DD} = 25 \text{ V}, \text{ starting } T_{Ch} = 25 ^{\circ}\text{C}, \text{ L} = 7 \text{ mH}, \text{ R}_{G} = 25 ^{\circ}\text{C}, \text{ I}_{AR} = 5 \text{ A}$ 

Note 2: Repetitive rating; pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

#### Industrial Applications

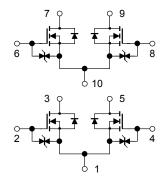
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Weight: 2.1 g (typ.)

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# **Array Configuration**



### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit	
Thermal resistance from channel to ambient	ΣR <sub>th (ch-a)</sub>	31.2	°C/W	
(4-device operation, Ta = 25°C)	. (* /			
Maximum lead temperature for soldering purposes	TL	260	°C	
(3.2 mm from case for t = 10 s)				

# Electrical Characteristics (Ta = 25°C)

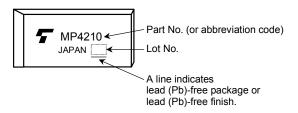
Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μA
Drain cut-off curre	ent	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V	_	_	100	μΑ
Drain-source brea	akdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	60	_	_	V
Gate threshold vo	oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	0.8	_	2.0	V
Drain-source ON resistance		Pro (au)	V <sub>GS</sub> = 4 V, I <sub>D</sub> = 2.5 A	_	0.21	0.32	Ω
		R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2.5 A		0.12	0.16	1 1
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 2.5 A	3.0	5.0	_	S
Input capacitance	;	C <sub>iss</sub>	V 10 V V 0 V	_	370	_	pF
Reverse transfer capacitance Output capacitance		C <sub>rss</sub>	- V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V - f = 1 MHz	_	60	_	pF
		Coss		_	180	_	pF
Turn-on ti Switching time Fall time	Rise time	t <sub>r</sub>	$V_{GS}$ $V_{OD} \approx 30 \text{ V}$ $V_{IN}$ : $t_r$ , $t_f < 5 \text{ ns, duty} \le 1\%$ , $t_W = 10 \text{ µs}$	_	18	_	- ns
	Turn-on time	t <sub>on</sub>		ı	25	_	
	Fall time	t <sub>f</sub>		1	55	_	
	Turn-off time	t <sub>off</sub>		1	170	_	
Total gate charge (gate-source plus gate-drain)		Qg	V <sub>DD</sub> ≈ 48 V, V <sub>GS</sub> = 10 V	_	12	_	nC
Gate-source charge		Q <sub>gs</sub>	I <sub>D</sub> = 5 A	_	8		nC
Gate-drain ("miller") charge		Q <sub>gd</sub>		_	4	_	nC

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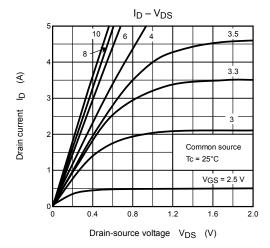
# Source-Drain Diode Ratings and Characteristics (Ta = 25°C)

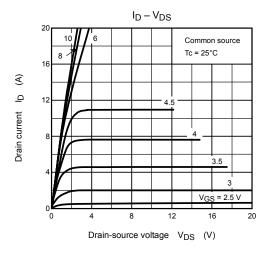
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current	I <sub>DR</sub>	_	_	_	5	Α
Pulse drain reverse current	I <sub>DRP</sub>	_	_	_	20	Α
Diode forward voltage	V <sub>DSF</sub>	I <sub>DR</sub> = 5 A, V <sub>GS</sub> = 0 V	_	_	-1.7	٧
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 5 A, V <sub>GS</sub> = 0 V	_	70	_	ns
Reverse recovery charge	Q <sub>rr</sub>	dl <sub>DR</sub> /dt = 50 A/μs	_	0.1	_	μC

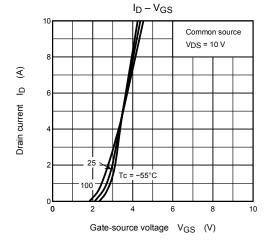
### Marking

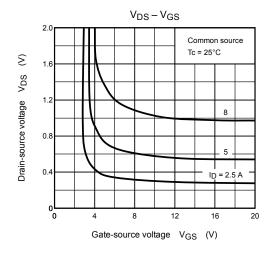


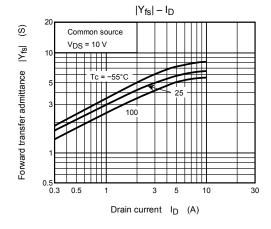
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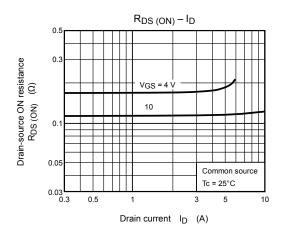




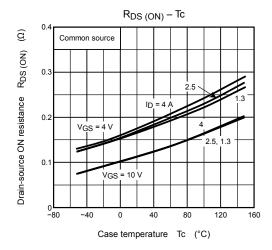


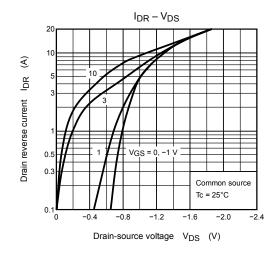


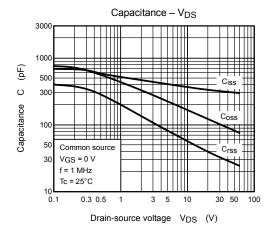


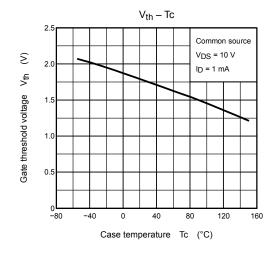


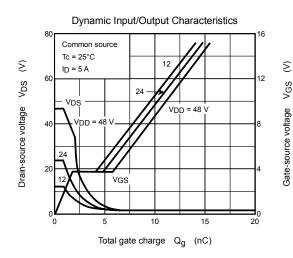
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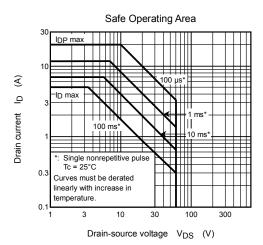


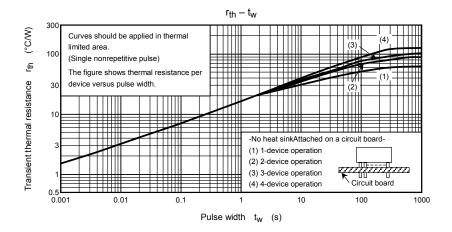


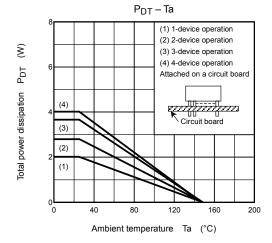


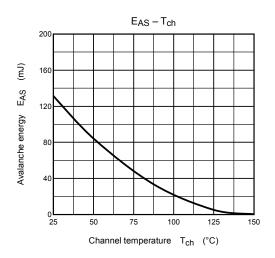


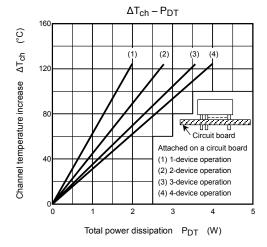


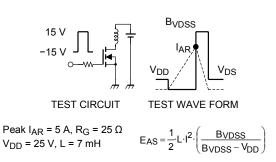












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